

Applications

- General purpose wireless
- Femtocells
- Repeaters
- Data cards and dongles

Product Features

- Usable bandwidth 25 MHz
- No matching required for operation at 50Ω
- Excellent rejection for Bluetooth and GPS operation
- No matching for 50 ohm environment
- High Isolation
- High Rejection
- Ceramic Surface Mount Package (SMP)
- Small Size: 3.8 x 3.8 x 1.47 mm
- Hermetic RoHS compliant, Pb-free

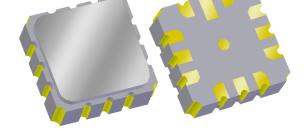


General Description

856908 is a Band V duplexer in a compact size for use in Femtocells, coverage enhancement repeaters, data cards, and other wireless data applications. Designed for rejection of unwanted Bluetooth and GPS signals, this SAW duplexer also has excellent power handling capability for low power transmitters.

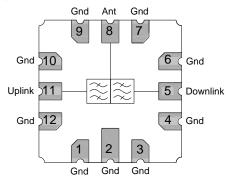
Housed in a 3.8 x 3.8 mm hermetic package, this device allows for a compact and cost effective duplexer solution for Band V applications.

No matching components are required, making the PCB design and implementation easy.



Functional Block Diagram

Top view



Pin Configuration

| Pin # SE | Description |
|-----------|-------------|
| 5 | Downlink |
| 8 | Antenna |
| 11 | Uplink |
| 1,2,3,4,6 | Case Ground |
| 7,9,10,12 | Case Ground |

Ordering Information

| Part No. | Description | |
|------------|------------------|--|
| 856908 | packaged part | |
| 856908-EVB | evaluation board | |

Standard T/R size =4000 units/reel.

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Specifications

Electrical Specifications (1)

Specified Temperature Range: (2) -30 to +85 °C

| Uplink Specifications | | | | | |
|------------------------------------|-----------------|------|-------------|-----|--------|
| Parameter (3) | Conditions | Min | Typical (4) | Max | Units |
| Center Frequency | | - | 836.5 | - | MHz |
| Maximum Insertion Loss | 824 – 849 MHz | - | 2.0 | 2.5 | dB |
| Amplitude Ripple | 824 – 849 MHz | - | 0.25 | 1.0 | dB p-p |
| Absolute Attenuation | 869 – 894 MHz | 42.5 | 44.7 | - | dB |
| | 1574 – 1577 MHz | 38 | 42.4 | - | dB |
| | 1648 – 1698 MHz | 35 | 45 | - | dB |
| | 1850 – 2170 MHz | 27 | 35.7 | - | dB |
| | 2472 – 2547 MHz | 15 | 22.6 | - | dB |
| Return Loss at Uplink Terminal (5) | 824 – 849 MHz | 9.5 | 12 | - | dB |
| Input Power (6) | 824 – 849 MHz | | | +27 | dBm |

| Downlink Specifications | | | | | |
|--------------------------------------|-----------------|-----|-------------|-----|--------|
| Parameter (3) | Conditions | Min | Typical (4) | Max | Units |
| Center Frequency | | - | 881.5 | - | MHz |
| Maximum Insertion Loss | 869 – 894 MHz | - | 2.5 | 3.5 | dB |
| Amplitude Ripple | 869 – 894 MHz | - | 0.4 | 2.2 | dB p-p |
| Absolute Attenuation | 824 – 849 MHz | 50 | 55.3 | - | dB |
| | 1570 – 1580 MHz | 40 | 56.0 | - | dB |
| | 1850 – 2170 MHz | 33 | 41.0 | - | dB |
| | 2400 – 2484 MHz | 15 | 23.4 | - | dB |
| Return Loss at Downlink Terminal (5) | 869 – 894 MHz | 9.5 | 10.8 | - | dB |
| Input Power (6) | 869 – 894 MHz | | | +24 | dBm |

| Uplink-Downlink Specifications | | | | | |
|--|---------------|-----|-------------|-----|-------|
| Parameter (3) | Conditions | Min | Typical (4) | Max | Units |
| Uplink-Downlink Isolation | 824 – 849 MHz | 50 | 56.9 | - | dB |
| | 849 – 869 MHz | 34 | 38.4 | - | dB |
| | 869 – 894 MHz | 45 | 46.4 | - | dB |
| Source/Load Impedance (single-ended) (7) | | - | 50 | - | Ω |

Notes:

- 1. All specifications are based on the TriQuint schematics for the reference designs shown on page 3
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 4. Typical values are based on average measurements at room temperature on pcb
- 5. Excluding losses due to PCB
- 6. CW signal at 55°C for 10,000 hours
- 7. This is the optimum impedance in order to achieve the performance shown

Absolute Maximum Ratings

| • | |
|----------------------|--|
| Parameter | Rating |
| Operable Temperature | $-40 \text{ to } +85 ^{\circ}\text{C}$ |
| Storage Temperature | $-40 \text{ to } +85 ^{\circ}\text{C}$ |

Operation of this device outside the parameter ranges given above may cause permanent damage.

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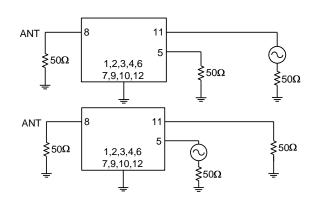


Reference Design -50Ω SE Input, 50Ω SE Output

Schematic

Uplink 50Ω Single-ended Input

Downlink 50Ω Single-ended Input



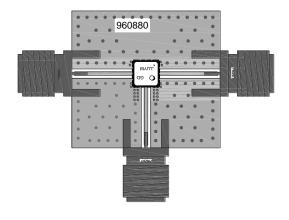
 $\begin{array}{c} 50\,\Omega\\ Single-ended\\ Output \end{array}$

 $\begin{array}{c} 50\,\Omega\\ Single-ended\\ Output \end{array}$

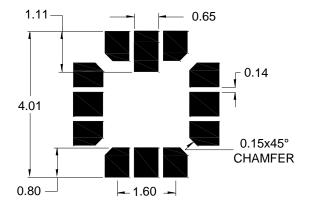
Notes:

- 1. No impedance matching required
- 2. Actual matching values may vary due to PCB layout and parasitic

PC Board



Mounting Configuration



Notes:

Top, middle & bottom layers: 1 oz copper Substrates: FR4 dielectric, .031" thick

Finish plating: Nickel: 3-8 µm thick, Gold: .03-.2 µm thick

Hole plating: Copper min .0008µm thick

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Notes:

- 1. All dimensions are in millimeters.
- 2. This footprint represents a recommendation only.

Bill of Material

| Reference Desg. | Value | Description Manufacturer | | Part Number | |
|-----------------|-------|--------------------------|------------------|---------------|--|
| SMA | N/A | SMA connector | Radiall USA Inc. | 9602-1111-018 | |
| PCB | N/A | 3-layer | multiple | 960880 | |

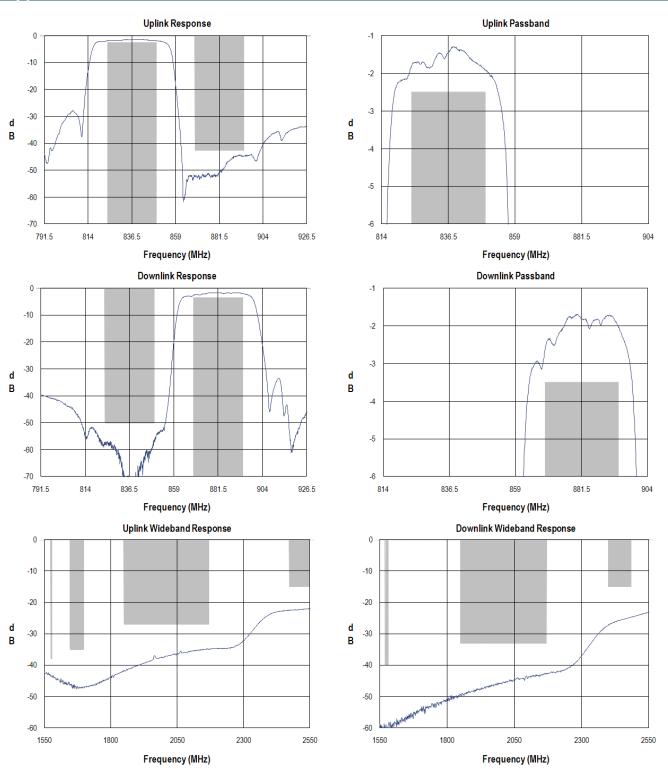
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Typical Performance (at room temperature)

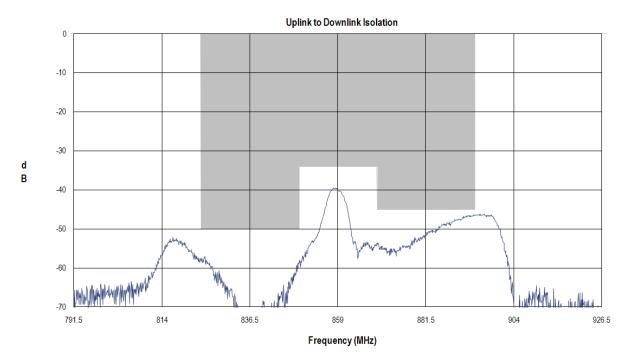


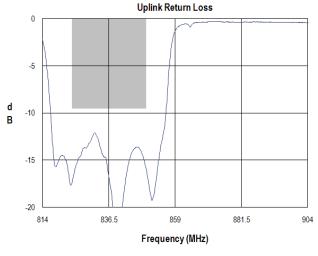
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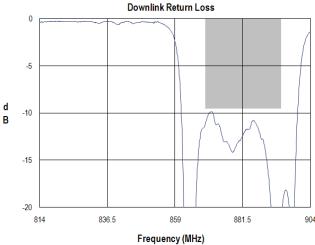
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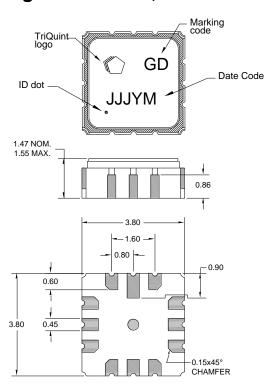


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Mechanical Information

Package Information, Dimensions and Marking



Package Style: SMP-15N Dimensions: 3.8 x 3.8 x 1.47 mm

Body: Al_2O_3 ceramic Lid: Kovar, Ni plated

Terminations: Au plating 0.5 - 1.0μm, over a 2-6μm Ni

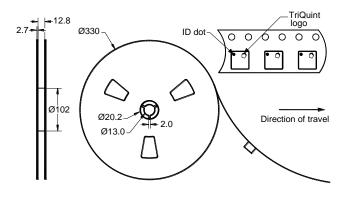
plating

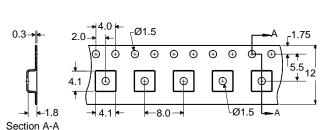
All dimensions shown are nominal in millimeters All tolerances are $\pm 0.15 mm$ except overall length and width $\pm 0.10 mm$

The date code consists of: day of the current year (Julian, 3 digits), $Y = last \ digit \ of \ the \ year, \ and \ M = manufacturing \ site \ code$

Tape and Reel Information

Standard T/R size = 4000 units/reel. All dimensions are in millimeters





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Product Compliance Information

ESD Information



Caution! ESD-Sensitive Device

ESD Rating: 1A

Value: Passes ≥ 300 V min.

Test: Human Body Model (HBM)

Standard: JEDEC Standard JESD22-A114

ESD Rating: B

Value: Passes $\geq 200 \text{ V min.}$ Test: Machine Model (MM)

Standard: JEDEC Standard JESD22-A115

MSL Rating

Devices are Hermetic, therefore MSL is not applicable

Solderability

Compatible with the latest version of J-STD-020, lead free solder, 260°C

Refer to **Soldering Profile** for recommended guidelines.

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A $(C_{15}H_{12}Br_4O_2)$ Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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